

/ Descriptions

SOT-323

NPN

Silicon NPN transistor in a SOT-323 Plastic Package.

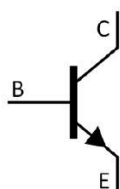
• / Features

Low C_{ob} .

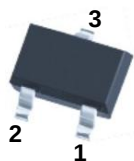
▼ / Applications

General amplifier.

≈ / Equivalent Circuit



⏏ / Pinning



PIN1 Emitter

PIN 2 Base

PIN 3 Collector

. ⏏ / Marking

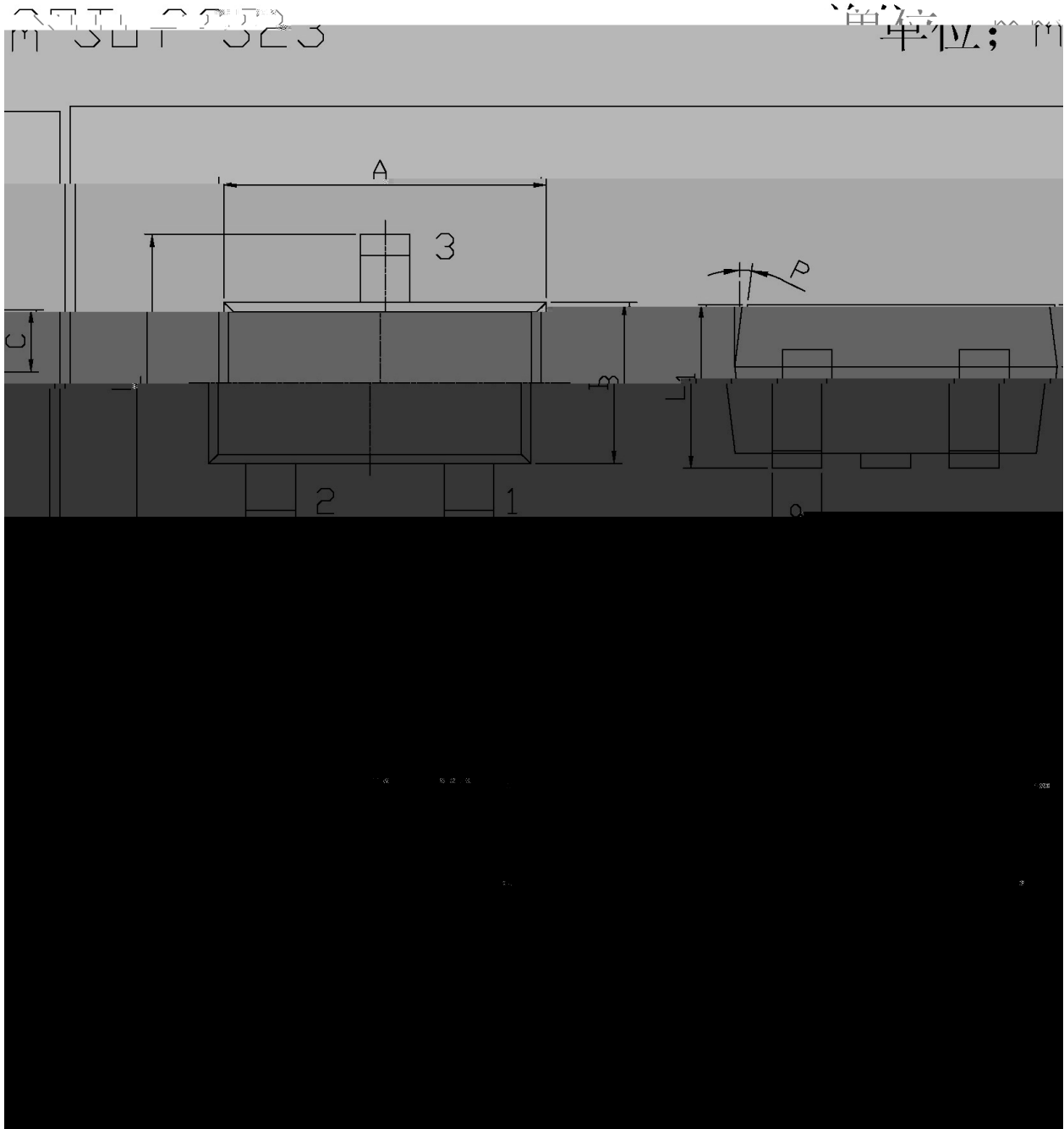
h_{FE} Classifications Symbol	Q	R	S
h_{FE} Range	120 270	180 390	270 560
Marking	HBQ	HBR	HBS

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	60	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	7.0	V
Collector Current - Continuous	I_C	150	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

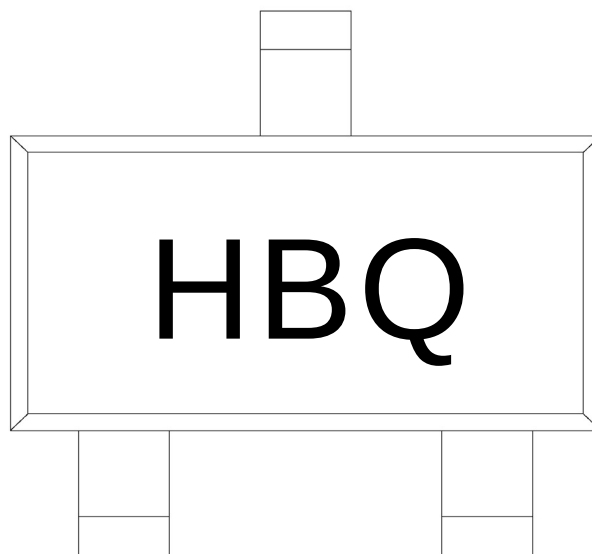
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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Collector to Base Breakdown 6 -1.6743 TD0540078 n5 55.98 438.8003 Tm-0.0026Tw()Tj10.5 0 0 10V.1 424.Q5 64.

/ Package Dimensions



/ Marking Instructions



H

B

Q

h_{FE}

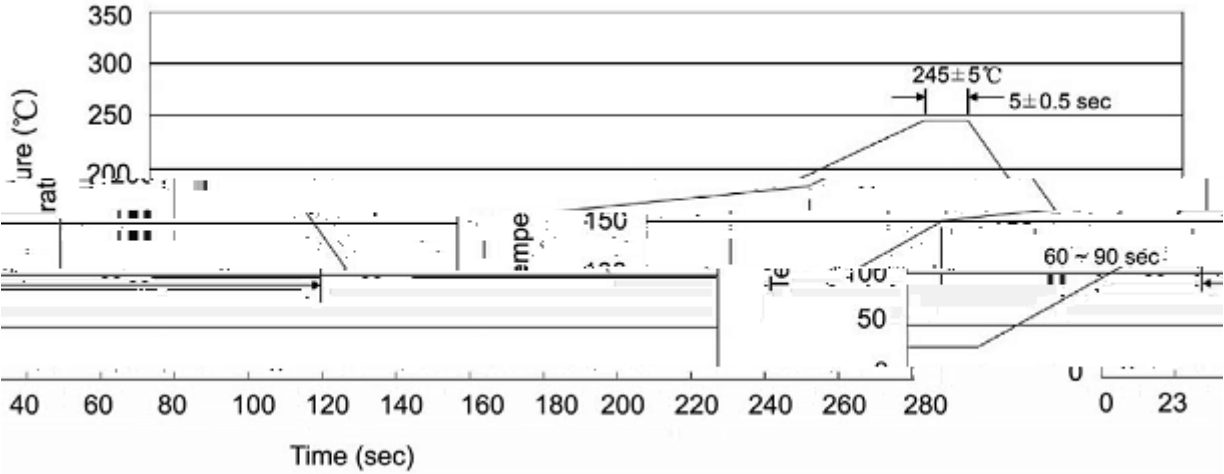
Note:

H: Company Code.

B: Product Type.

Q: h_{FE} Classifications Symbol

1. Thermal Characteristics



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

2. Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

3. Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-323	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

4. Notices